

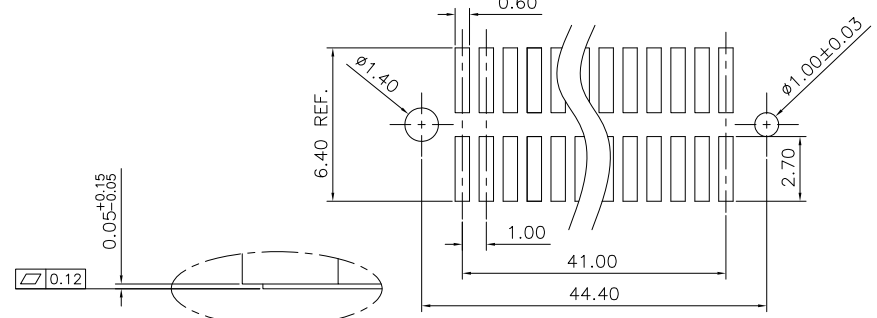
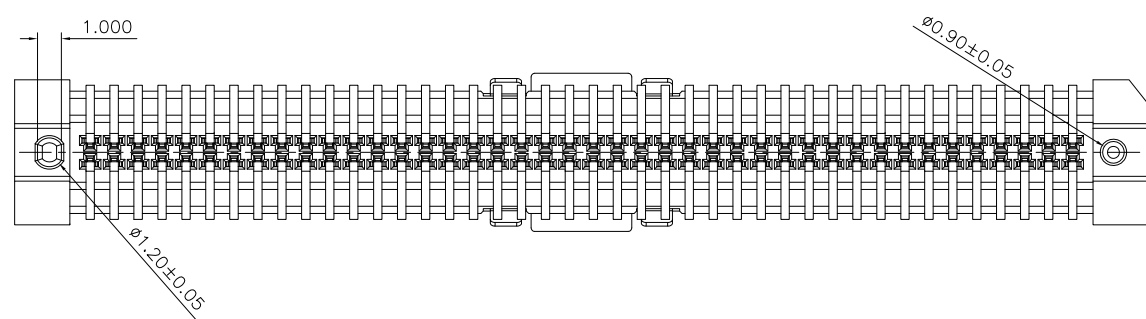
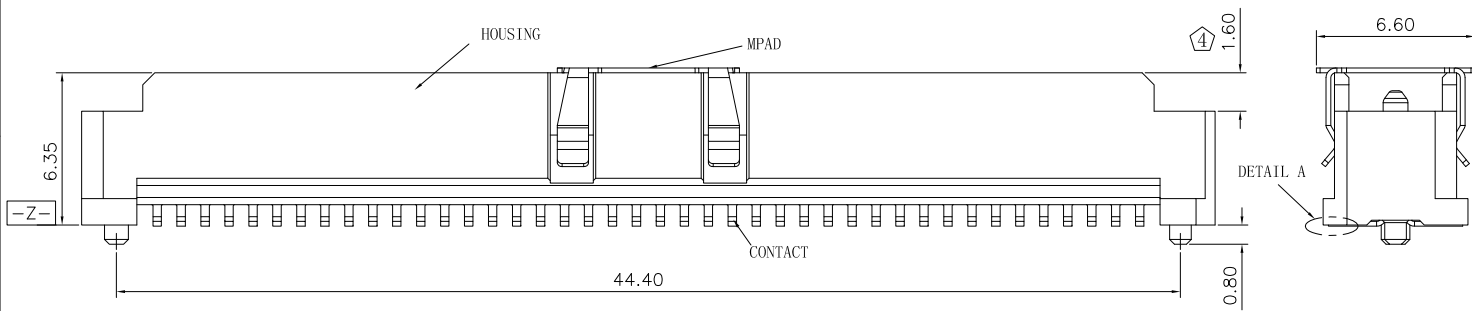
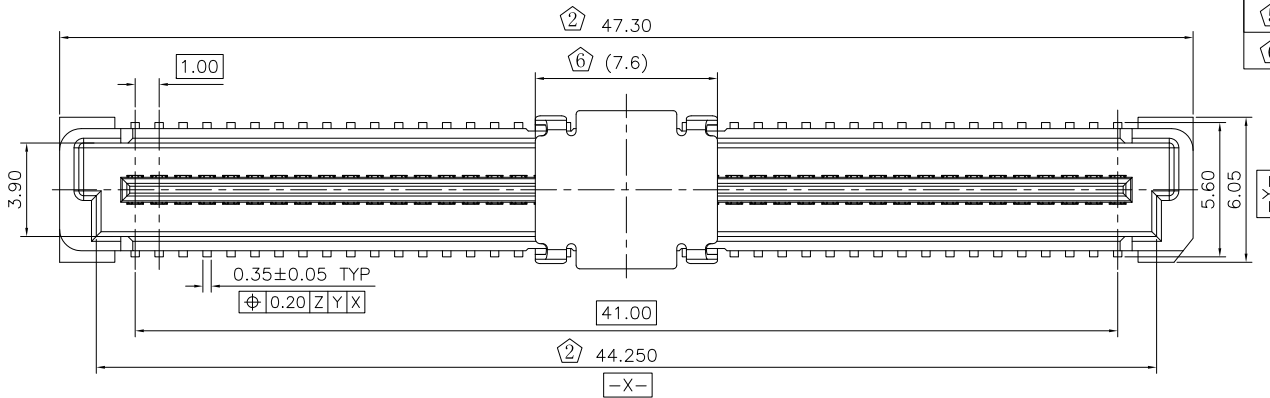
REV.	ECN Number	Description	Drawn
1	CS18120393	RELEASE	XPG_2018.12.27
②	E19010007	Modify Interface (Mated)	XPG_2019.01.03
③	E19010025	Add plating code:3	SJ_2019.01.17
④	E19010040	Modify Shape	XPG_2019.01.29
⑤	E19040019	Modify MPAD & Insertion Force	Peak_2019.04.24
⑥	E20080033	Modify MPAD	Peak_2020.08.31

- NOTES: (UNLESS OTHERWISE SPECIFIED)
 1. DIMENSION SHALL BE INTERPRETED PER ANSI Y14.5M-1994.
 2. MATERIAL:
 HOUSING MATERIAL: HIGH TEMPERATURE PLASTICS.
 CONTACT MATERIAL: COPPER ALLOY,
 MPAD MATERIAL: STAINLESS STEEL.
 3. ELECTRICAL SPECIFICATION:
 CONTACT RESISTANCE: 30 m ohms Max(Initial).
 INSULATION RESISTANCE: 1000M ohms Min.
 CURRENT RATING: 1.0A.
 DIELECTRIC WITHSTANDING VOLTAGE: 250V AC
 4. MECHANICAL SPECIFICATION:
 INSERTION FORCE: 90gf Max. Per Pin. ⑤
 WITHDRAWAL FORCE: 10gf Min. Per Pin.
 5. PRODUCT NUMBER MATRIX:

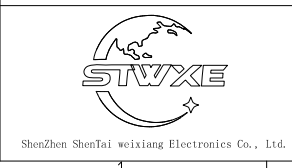
B B 5 1-84 A T- 1 - X H B

BTB	Series code	1.00 Pitch	Plug	PIN No.	84:84PIN	Height	Soldering Type	BTB	Packing:
						A: H=6.35mm	T:SMT		B: REEL+MPAD
									H: Halogen free
									Plating

Definition		Code	
◎ Duplex plated			
flash	K	1u"	S 3u"
	M	10u"	N 15u"
	Q	25u"	T 30u"
		2u"	3



RECOMMENDED PCB LAYOUT
 TOLERANCE ±0.05



TOLERANCE UNLESS OTHERWISE SPECIFIED			
X.X	±0.30	X.°	±3°
X.XX	±0.20	X.X°	±2°
X.XXX	±0.10	X.XX°	±1°

SCALE	1:1
UNIT	mm
SIZE	A4

ORIGINAL DRAWN:	Peak	DATE	2020.08.31
CHECK:	Xu peiguang	DATE	2020.08.31
APPROVE:	Ady zhou	DATE	2020.08.31

DWG. NO.	600-0000-0430
PARTS NO. (INTENDED USE)	BB51-84AT-1-XHB

TITLE	BB51-84AT CUSTOMER DRAWING
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REV.	6
SHEET	1/1